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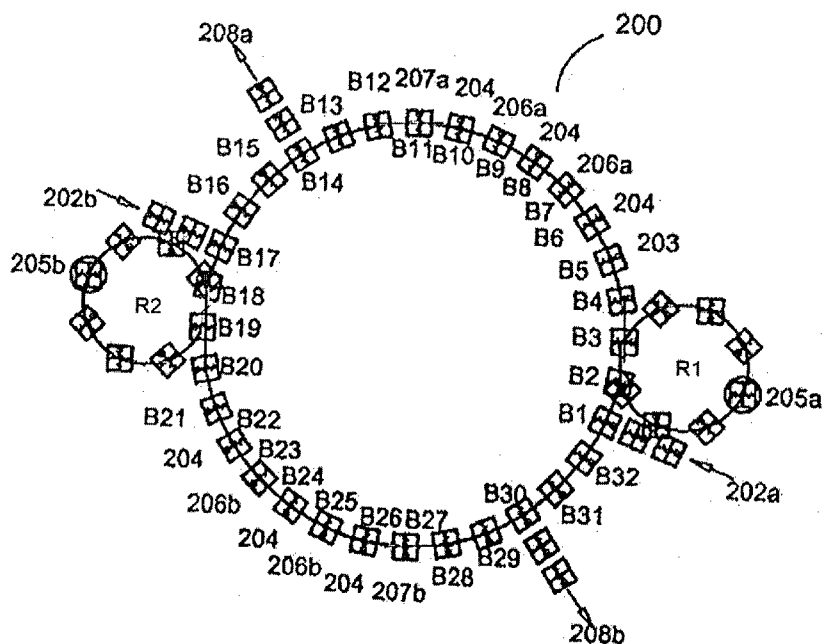
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(54) Title: A SEMICONDUCTOR COMPONENTS DELIVERY SYSTEM ASSOCIATED WITH A TURRET TYPE TESTING APPARATUS



(57) Abstract: The invention discloses a semiconductor components delivery system associated with a turret type testing apparatus for testing integrity and functionality of semiconductor components wherein at least two input feeders loadable with semiconductor components to be vision checked, tested and/or packed are provided. The delivery system is also provided with multiple output means such as a tube, a tape or a bin or a combination thereof for semiconductor components determined to be non defective.

